



Final Product/Process Change Notification

Document #:FPCN26815X

Issue Date:26 Sep 2025

Title of Change:	Transfer of Wafer Plating Process for Standard Cascode and Combo FET Products from PacTech US to PacTech Malaysia							
Proposed First Ship date:	02 Jan 2026 or earlier if approved by customer							
Contact Information:	Contact your local onsemi Sales Office							
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.							
Additional Reliability Data:	Contact your local onsemi Sales Office							
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com							
Marking of Parts/ Traceability of Change:	Changed material can be identified by date code or lot code							
Change Category:	Wafer Fab Change							
Change Sub-Category(s):	Manufacturing Site Transfer							
Sites Affected:								
onsemi Sites	External Foundry/Subcon Sites							
None	Pactech, Asia							
Description and Purpose:								
<p>onsemi wishes to inform customers of its plan to transfer the wafer plating process for Standard Cascode and Combo FET products from PacTech US to PacTech Malaysia.</p> <p>This change is driven by the shutdown of PacTech US operations and aims to continue production at PacTech Malaysia without impacting product materials or electrical characteristics.</p>								
<table border="1"> <thead> <tr> <th>Item Being Changed</th> <th>From</th> <th>To</th> </tr> </thead> <tbody> <tr> <td>Site</td> <td>Wafer plating at PacTech US</td> <td>Wafer plating at PacTech Malaysia</td> </tr> </tbody> </table>			Item Being Changed	From	To	Site	Wafer plating at PacTech US	Wafer plating at PacTech Malaysia
Item Being Changed	From	To						
Site	Wafer plating at PacTech US	Wafer plating at PacTech Malaysia						
There are no product material changes and no product marking change.								



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Reliability Data Summary:

QV DEVICE NAME: UF3SC120040B7S – Standard Cascode

PACKAGE: TO263 7L

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias (HTRB)	MILSTD750-1 Method M1038A	Tj= 175°C, V=100% rated, 1008 hrs	1008 hrs	0/231
Intermittent Operating Life + Preconditioning (IOL + PC)	MIL-STD-750 Method 1037	Ta=+25°C, delta Tj=100°C On/Off = 5 min, 3000 cyc	3000 cyc	0/231
Temperature Cycling + Preconditioning (TC + PC)	JESD22 A104; Q101 Appendix 6	Ta= -55°C to +150°C, 1000 cyc	1000 cyc	0/231
Autoclave + Preconditioning (AC + PC)	JESD22 A102	Ta = 121°C, P= 15 PSIG, RH = 100%, 96 hrs	96 hrs	0/231
High Humidity High Temp Rev Bias + Preconditioning (H3TRB + PC)	JEDS22 A101	Ta = 85°C, 85% RH, V=100V, 1008hrs	1008 hrs	0/231

QV DEVICE NAME: UG4SC120009K4SH – Combo FET

PACKAGE: TO247 4L

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias (HTRB)	MILSTD750-1 Method M1038A	Tj= 175°C, V=100% rated, 1008 hrs	1008 hrs	0/225
High Temperature Gate Bias (HTGB JFET)	JESD22-A108	Tj = 175°C for 1008 hours, -31V	1008 hrs	0/229
High Temperature Gate Bias (HTGB JFET)	JESD22-A108	Tj = 175°C for 1008 hours, -21V	1008 hrs	0/231
Intermittent Operating Life + Preconditioning (IOL + PC)	MIL-STD-750 Method 1037	Ta=+25°C, delta Tj=100°C On/Off = 5 min, 3000 cyc	3000 cyc	0/231
Temperature Cycling + Preconditioning (TC + PC)	JESD22 A104; Q101 Appendix 6	Ta= -55°C to +150°C, 1000 cyc	1000 cyc	0/231
Autoclave + Preconditioning (AC + PC)	JESD22 A102	Ta = 121°C, P= 15 PSIG, RH = 100%, 96 hrs	96 hrs	0/231
High Humidity High Temp Rev Bias + Preconditioning (H3TRB + PC)	JEDS22 A101	Ta = 85°C, 85% RH, V=100V, 1008hrs	1008 hrs	0/231

Electrical Characteristics Summary:

Electrical characteristics are not impacted.



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List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
UF4SC120009K4SH	UF3SC120040B7S, UG4SC12009K4SH
UF3SC120040B7S	UF3SC120040B7S, UG4SC12009K4SH
UF3SC120016K3S	UF3SC120040B7S, UG4SC12009K4SH
UF3SC120009K4S	UF3SC120040B7S, UG4SC12009K4SH
UF3SC065040B7S	UF3SC120040B7S, UG4SC12009K4SH
UF3SC065030B7S	UF3SC120040B7S, UG4SC12009K4SH
UF3SC120016K4S	UF3SC120040B7S, UG4SC12009K4SH
UF3SC065007K4S	UF3SC120040B7S, UG4SC12009K4SH
UF4SC120023B7S	UF3SC120040B7S, UG4SC12009K4SH
UCSDG130SC12M88C3N	UF3SC120040B7S, UG4SC12009K4SH
UG4SC120002SNS	UF3SC120040B7S, UG4SC12009K4SH
UHB100SC12E1BC3N	UF3SC120040B7S, UG4SC12009K4SH
UHB50SC12E1BC3N	UF3SC120040B7S, UG4SC12009K4SH
UJ4SC075005L8S	UF3SC120040B7S, UG4SC12009K4SH
UJ4SC075006K4S	UF3SC120040B7S, UG4SC12009K4SH
UJ4SC075006K4S-D	UF3SC120040B7S, UG4SC12009K4SH
UJ4SC075008L8S	UF3SC120040B7S, UG4SC12009K4SH
UJ4SC075009B7S	UF3SC120040B7S, UG4SC12009K4SH
UJ4SC075009K4S	UF3SC120040B7S, UG4SC12009K4SH
UJ4SC075010L8S	UF3SC120040B7S, UG4SC12009K4SH
UJ4SC075011B7S	UF3SC120040B7S, UG4SC12009K4SH
UJ4SC075011K4S	UF3SC120040B7S, UG4SC12009K4SH
UJ4SC075018B7S	UF3SC120040B7S, UG4SC12009K4SH
UJ4SC075018L8S	UF3SC120040B7S, UG4SC12009K4SH
UG4SC075005L8S	UF3SC120040B7S, UG4SC12009K4SH
UFB25SC12E1BC3N	UF3SC120040B7S, UG4SC12009K4SH
UF4SC120030K4S	UF3SC120040B7S, UG4SC12009K4SH
UF4SC120030B7S	UF3SC120040B7S, UG4SC12009K4SH
UF4SC120023K4S	UF3SC120040B7S, UG4SC12009K4SH